

Description

The CY2569, a highly integrated USB Type-C PD3.0/PPS sink controller, is targeted for DC power request and control for a Type-C Connector equipped Devices (TCD). To leveraging increasing popularity of standard Type-C PD3.0 power adaptors, the CY2569 negotiates with an existing PD3.0 adaptor to acquire the required power profile to supply the TCD.

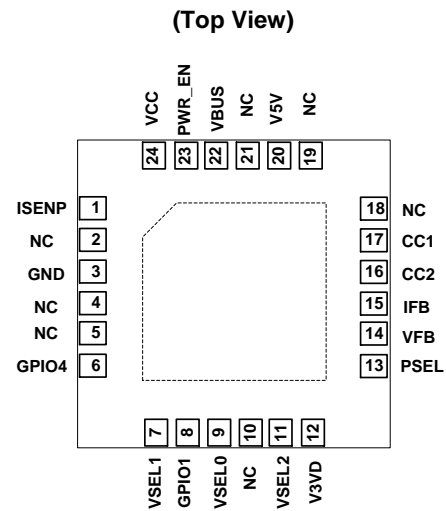
Working its role as DC-Power request from a USB PD source, the CY2569 interprets power input requirements (voltage/current and maximum power) from the TCD, and then establishes power link through configuration channel (CC) communication with an external USB PD3.0 adaptor to output a suitable DC power for TCD device. The voltage requests could be easily specified by 3 pins (VSEL2, VSEL1, VSEL0), up to 8 voltages can be selected and both fixed PDO (Power Data Object) and PPS APDO (Augmented Power Data Object) in PD source adapter are supported in CY2569 search algorithm. Also, up to 10 maximum power levels can be selected through different resistance value of the resistor connected to pin PSEL (refer to figure 1 and 2).

There are rich power functions embedded as hardware or enabled by built-in firmware in the chip so as to reduce total BOM while maintain maximum flexibility. A one-time-programming (OTP) ROM is provided to store the PD/Sink controller firmware.

Features

- Compliant with USB PD Rev 3.0 v1.2
- USB-IF certificated TID: 5000
- Ease of use without any firmware programming
- Up to 8 Voltage selections by 3-pin setting
- Support dynamic pin setting with periodic scanning
- Up to 10 Power selections by 1-pin attached resistor
- Support OVP with hard reset and auto restart
- Support Driver for N-MOS VBUS Power Switch
- Support Dead-battery mode
- Support LED indication of charging and fault status
- Operating Voltage Range: 3.3V to 24V
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Pin Assignments



W-QFN4040-24 (Type A1)

Applications

- Type-C Connector Equipped Battery-Powered Devices
- Type-C Connector Equipped DC-Power Input Devices
- Type-C-to-Traditional Barrel Connector Power Adaptor Cables

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. Contact <http://www.canyon-semi.com.tw> for more information of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

USB Type-C® and USB-C® are registered trademarks of USB Implementers Forum.

Typical Applications Circuit

The CY2569 is an USB Type-C power delivery sink controller and used to request a specific power profile from a standard USB PD 3.0 compliance source adapter, as shown in the figure below.

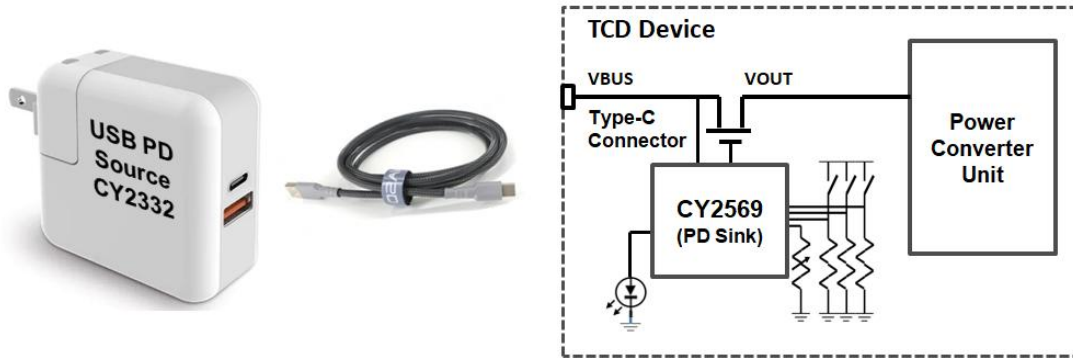


Figure 1. Typical Application structure of CY2569

The CY2569 can request a power through resistor setting. A typical setting of CY2569 to get a DC power is shown as below.

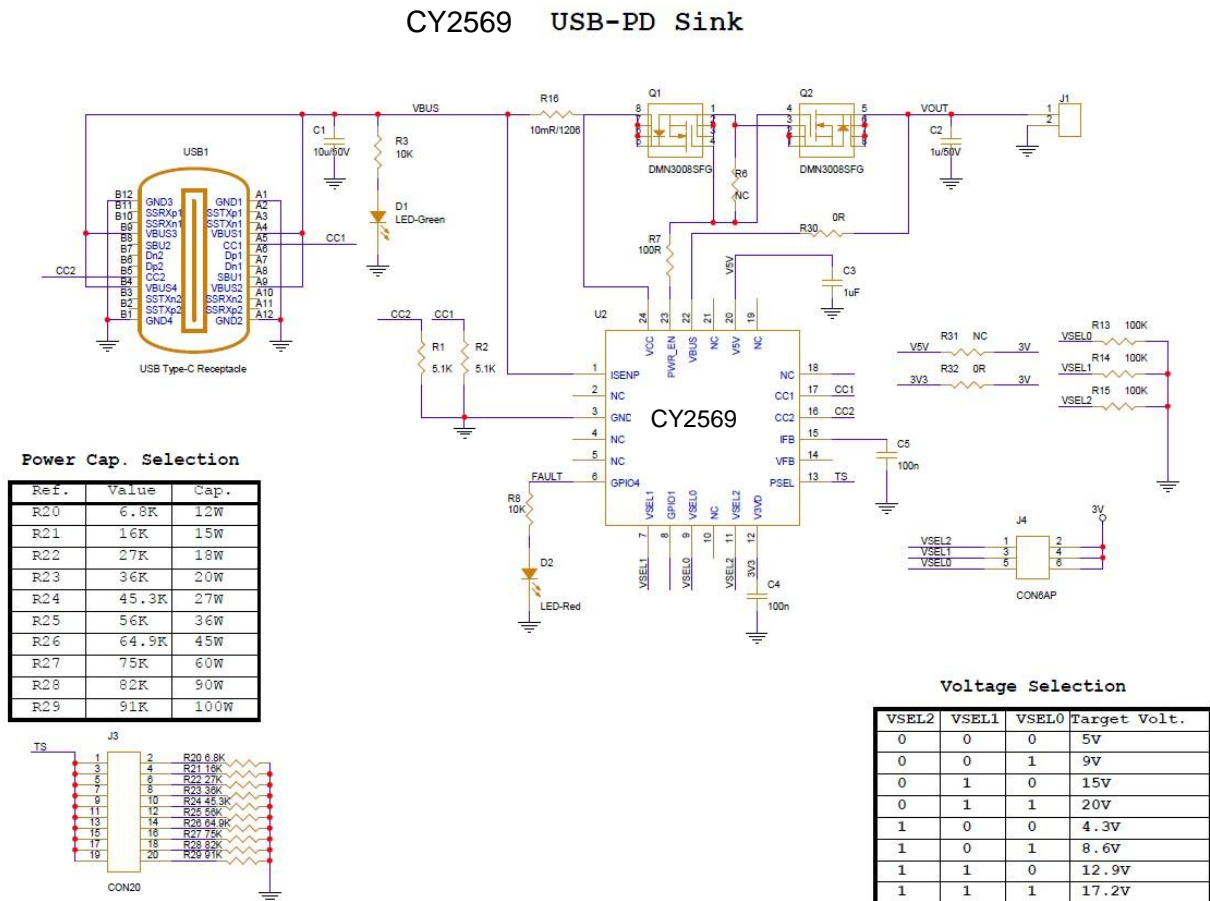


Figure 2. Typical Application Circuit of CY2569

Pin Descriptions

Pin No	Pin Name	Type (Note)	Pin Function
1	ISENP	AIO	Current Sense Positive Node.
2	NC	-	No Connection
3	GND	GND	Ground
4	NC	-	No Connection
5	NC	-	No Connection
6	GPIO4	DIO	General Purpose Input/Output pin, for LED usage.
7	VSEL1	DIO	For Voltage Select Pin1
8	GPIO1	DIO	General Purpose Input / Output
9	VSEL0	DIO	For Voltage Select Pin0
10	NC	-	No Connection
11	VSEL2	DIO	For Voltage Select Pin2
12	V3VD	DP	3.3V LDO Output. Power for Digital circuit and Digital I/O pins, with 0.1uF to Ground
13	PSEL	AIO	For Power Capability Selection.
14	VFB	AI	For Voltage Measurement.
15	IFB	AI	For Current Measurement, with 100nF to Ground
16	CC2	AIO	Type-C configuration channel 2
17	CC1	AIO	Type-C configuration channel 1
18	NC	-	No Connection
19	NC	-	No Connection
20	V5V	AP	5V LDO output. Power for Analog circuit and Analog I/O pins, with 1uF to Ground
21	NC	-	No Connection
22	VBUS	AHV	Terminal for Discharge Path.
23	PWR_EN	AHV	To control external NMOS switch ON (High) or OFF (Low).
24	VCC	AHV	The power supply of the IC, connected to a ceramic capacitor.
-	EP	GND	Exposed pad is connected to Ground

Note:

AHV– Analog High Voltage pin

AP – Power for Analog Circuit and Analog I/O pins, 5.0V operation

AI – Analog Input pin

DP – Power for Digital Circuit and I/O pins, 3.3V operation

AIO – Analog I/O pin.

DIO – Digital I/O pin.

Functional Block Diagram

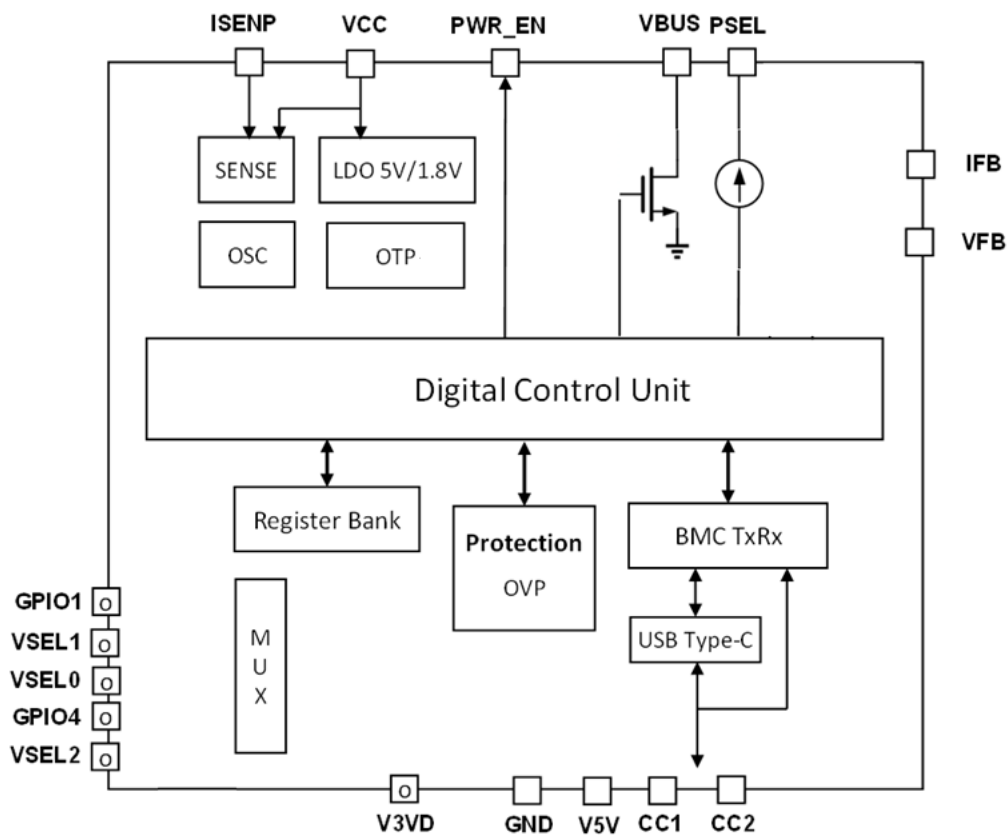


Figure 3. Functional Block Diagram of CY2569

Absolute Maximum Ratings (Note 4)

Symbol	Parameter	Rating	Unit
V_{VCC}	Input Voltage at VCC Pin	-0.3 to 24	V
$V_{FB}, V_{IFB}, V_{PSEL}$	Input Voltage at VFB, IFB, PSEL Pins	-0.3 to 7	V
$V_{VBUS}, V_{PWR_EN}, V_{ISENP}$	Input Voltage at VBUS, PWR_EN, ISENP Pins	-0.3 to 24	V
—	Voltage from PWR_EN to VCC Pin	-16 to 7	V
V_{V5V}	Input Voltage at V5V Pin	-0.3 to 7	V
V_{V3VD}	Input Voltage at V3VD Pin	-0.3 to 5	V
V_{CC1}, V_{CC2}	Input Voltage at CC1, CC2 Pins	-0.3 to 7	V
$V_{GPIO1}, V_{GPIO4}, V_{VSEL0} - V_{VSEL2}$	Input Voltage at GPIO1, GPIO4, VSEL0 – VSEL2 Pins	-0.3 to 5	V
T_J	Operating Junction Temperature	-40 to +150	°C
T_{STG}	Storage Temperature	-65 to +150	°C
T_{LEAD}	Lead Temperature (Soldering, 10s)	+300	°C
θ_{JA}	Thermal Resistance (Junction to Ambient) (Note 5)	28	°C/W
θ_{JC}	Thermal Resistance (Junction to Case) (Note 5)	16	°C/W
ESD	Human Body Model	2	kV
ESD	Charged Device Model	750	V

Notes: 4. Stresses greater than those listed under “*Absolute Maximum Ratings*” can cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “*Recommended Operating Conditions*” is not implied. Exposure to “*Absolute Maximum Ratings*” for extended periods can affect device reliability.
5. Test condition: Device mounted on FR-4 substrate PC board, 2oz copper, with the minimum footprint.

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Unit
V_{VCC}	Power Supply Voltage	3.3	24	V
$V_{VSEL0} \sim V_{VSEL2}$	Input Voltage at VSEL0 ~ VSEL2 Pins	0	3.7	V
V_{GPIO1}, V_{GPIO4}	Input Voltage at GPIO1, GPIO4 Pins	0	3.7	V
T_{OP}	Operating Temperature Range	-40	+85	°C

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
VCC SECTION						
V_{ST}	Startup Voltage	—	2.5	2.8	3.2	V
V_{UVLO}	Minimum Operating Voltage	—	2.4	2.7	3	V
V_{VCC_HYS}	V_{CC} Hysteresis ($V_{ST}-V_{UVLO}$)	—	0.05	—	—	V
I_{VCC_OPR}	Operating Supply Current	$V_{CC} = 5V$	—	3.3	6	mA
CC1/CC2 SECTION						
V_{L_RD3A}	Low Voltage Threshold Used to Distinguish R_D Attached or Detached for 3A Delivery	—	—	1.35	—	V
V_{H_RD3A}	High Voltage Threshold Used to Distinguish R_D Attached or Detached for 3A Delivery	—	—	2.0	—	V
VOLTAGE SELECTION AND POWER SELECTION						
V_{VSEL_HI}	$VSEL0 \sim VSEL2$ High Voltage (Note 7)	$V_{CC} = 5V$	1.4			V
V_{VSEL_LO}	$VSEL0 \sim VSEL2$ Low Voltage (Note 7)	$V_{CC} = 5V$			0.4	V
T_{VSEL_S}	$VSEL0 \sim VSEL2$ Scan Interval			250		ms
T_{VSEL_TD}	$VSEL0 \sim VSEL2$ Trap De-bounce			70		μs
I_{PSEL}	PSEL Current Source (Note 7)	—		20		μA
I_{PSEL_Range}	PSEL Current Source Range (Note 7)	—	-3		+3	%
GPIO SECTION						
V_{GPIO_HI}	GPIO1, GPIO4 High Voltage (Note 7)	$V_{CC} = 5V$	1.4			V
V_{GPIO_LO}	GPIO1, GPIO4 Low Voltage (Note 7)	$V_{CC} = 5V$			0.4	V
I_{GPIO}	GPIO1, GPIO4 Sink/Source Capability (Note 7)		2			mA
PROTECTION FUNCTION SECTION						
V_{OVP5V}	OVP_5V Enable Voltage (Note 6,7)	—		7		V
V_{OVP20V}	OVP_20V Enable Voltage (Note 6,7)	—		22		V
$t_{DEBOUNCE_OVP}$	OVP De-bounce Time (Note 8)	—	—	90	—	ms
I_{OVD}	Overvoltage Discharge Current	$V_{CC} = 5V$	150	200	250	mA
t_{OV_DELAY}	Delay from OVP Threshold Trip to NMOS Gate Turn-Off (Note 7)	—	—	—	50	ms

Notes: 6. 110% OVP setting @ $PDO > 18V$. $PDO + 2V$ OVP setting @ $PDO \leq 18V$.
7. Guaranteed by design
8. OVP blanking time during V_O transition from high output voltage to low output voltage, such as 9V to 5V, or 12V to 5V.

Performance Characteristics

Function Description

The CY2569, an USB Type-C power delivery Sink controller, meets USB Power Delivery specification rev 3.0 v1.2 (USB-IF certificated TID: 5000). It provides cost effective solution without the need of external discrete high voltage components like LDOs. During the protocol handshake process, packets are transmitted and received through the embedded BMC (Biphase Mark Coding) transceiver with good eye diagram and high noise immunity. Also, the OTP ROM is used to store main protocol, application firmware and system configuration parameters. The desired PDO for the CY2569-embedded TCD could be specified through a resistor setting scheme.

CC interface and BMC Transceiver

For the inter-operability consideration, CC interface detection and the BMC transceiver of CC are optimally designed to maintain its operating voltage tolerance and noise immunity.

USB Power Delivery Controller

To be in full compliant with the critical USB Power Delivery specification rev 3.0 v1.2, the CY2569 is implemented through the combination of hardware and OTP firmware, to leverage the quick response time in hardware and the flexibility in software.

Sink Voltage Selection

The CY2569 provide search algorithm for voltage request through High/Low voltage setting at VSEL0, VSEL1, and VSEL2 pins. While latches the pin setting at power on, the CY2569 also auto-scans and latches the pin setting periodically. Both fixed PDO and PPS APDO in PD source adapter are supported in CY2569 voltage search algorithm. With the 3-resistor-setting combination, the design could use the CY2569 to specify up to 8 voltage levels to fit the needs for a specific TCD.

Power Capability Selection

With a small constant current source outputs from PSEL pin, the CY2569 measures the voltage level at the PSEL pin with the attached resistor through internal ADC. Up to 10 Power selections are supported. The designers for TCDs are recommended to use the resistor with $\pm 1\%$ accuracy to connect to the PSEL pin to ensure request power selection.

NMOS VBUS Switch Control

Once the PDO negotiations are successful both in voltage selection and power selection, PWR_EN will enable NMOS VBUS switch. Any mismatch in voltage selection or power selection, NMOS VBUS switch is not turned on.

LED Indication

GPIO4 is used to control a LED flickering, and user can learn the system status according to the LED flashing pattern which is defined in the below Table-1. Any non-PD power source is not supported in CY2569, and LED will show mismatch accordingly.

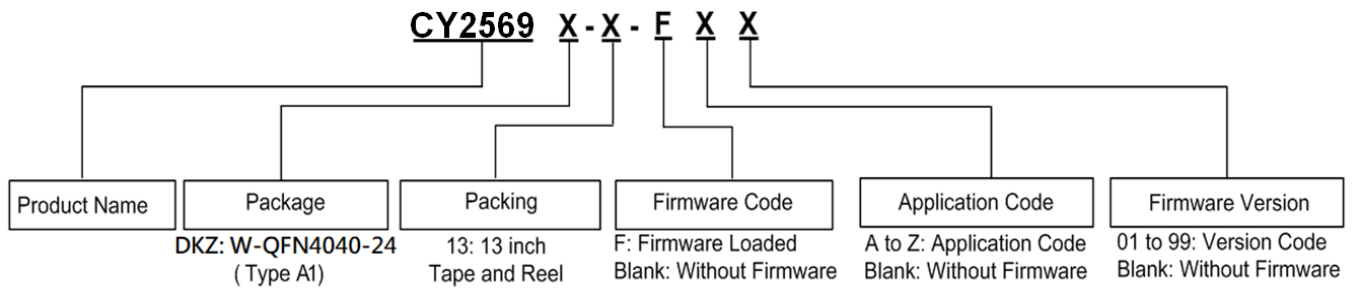
Condition	LED Pattern	Description
Charging	Breathing light (2sec dimming)	1 cycle is 4 sec
Fully charged	Always Light	Charging current < 500mA
Mismatch	1sec Flicker	Voltage or Power Mismatch. Non-PD power source. 1 cycle is 2 sec
Fault	300ms Flicker	OVP. 1 cycle is 600ms

Table 1 – LED Indication Table

OVP Protection

The CY2569 provides OVP feature by sending hard reset to the PD source when VBUS is higher than OVP voltage. Meanwhile, as soon as OVP is happened, it provides internal discharge path to reduce the overvoltage duration.

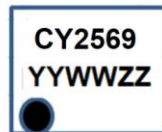
Ordering Information



Part Number	Package	Identification Code	13" Tape and Reel	
			Quantity	Part Number Suffix
CY2569DKZ-13	W-QFN4040-24 (Type A1)	CY2569	3000/Tape and Reel	-13

Marking Information

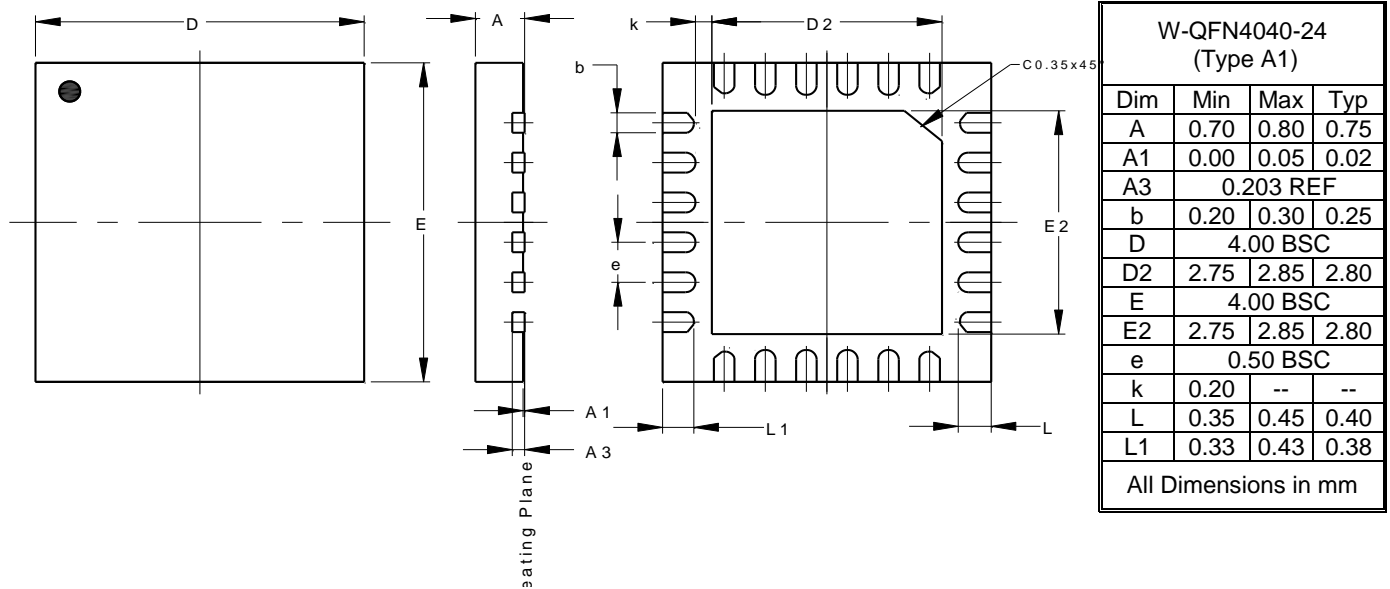
W-QFN4040-24



CY2569	Device Name
YYWW	YearWeek
ZZ	Internal Code

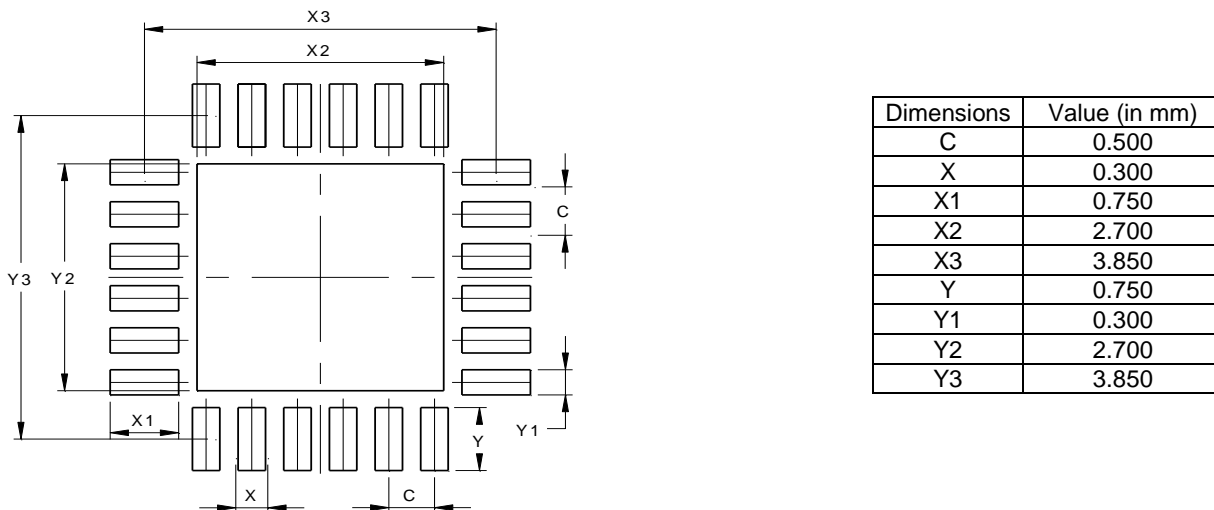
Package Outline Dimensions

W-QFN4040-24 (Type A1)



Suggested Pad Layout

W-QFN4040-24 (Type A1)



Mechanical Data

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per J-ESD-202
- Weight: 0.041 grams (Approximate)

IMPORTANT NOTICE

CANYON SEMICONDUCTOR INC. MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Canyon Semiconductor Inc. reserves the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Canyon Semiconductor Inc. does not assume any liability arising out of the application or use of this document or any product described herein; neither does Canyon Semiconductor Inc. convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Canyon Semiconductor Inc. and all the companies whose products are represented on Canyon Semiconductor Inc. website, harmless against all damages.

Canyon Semiconductor Inc. does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel.

Should Customers purchase or use Canyon Semiconductor Inc. products for any unintended or unauthorized application, Customers shall indemnify and hold Canyon Semiconductor Inc. and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Canyon Semiconductor Inc..

LIFE SUPPORT

Canyon Semiconductor Inc. products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Canyon Semiconductor Inc.. As used herein:

A. Life support devices or systems are devices or systems which:

1. are intended to implant into the body, or
2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Canyon Semiconductor Inc. products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Canyon Semiconductor Inc. Further, Customers must fully indemnify Canyon Semiconductor Inc. and its representatives against any damages arising out of the use of Canyon Semiconductor Inc. products in such safety-critical, life support devices or systems.

Copyright © 2022, Canyon Semiconductor Inc.

www.canyon-semi.com.tw